Zilog - Z8S18020FEC Datasheet

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Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	Z8S180
Number of Cores/Bus Width	1 Core, 8-Bit
Speed	20MHz
Co-Processors/DSP	-
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	5.0V
Operating Temperature	-40°C ~ 100°C (TA)
Security Features	-
Package / Case	80-BQFP
Supplier Device Package	80-QFP
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8s18020fec

GENERAL DESCRIPTION (Continued)

Power connections follow the conventional descriptions below:

Connection	Circuit	Device
Power	V_{CC}	V_{DD}
Ground	GND	V_{SS}

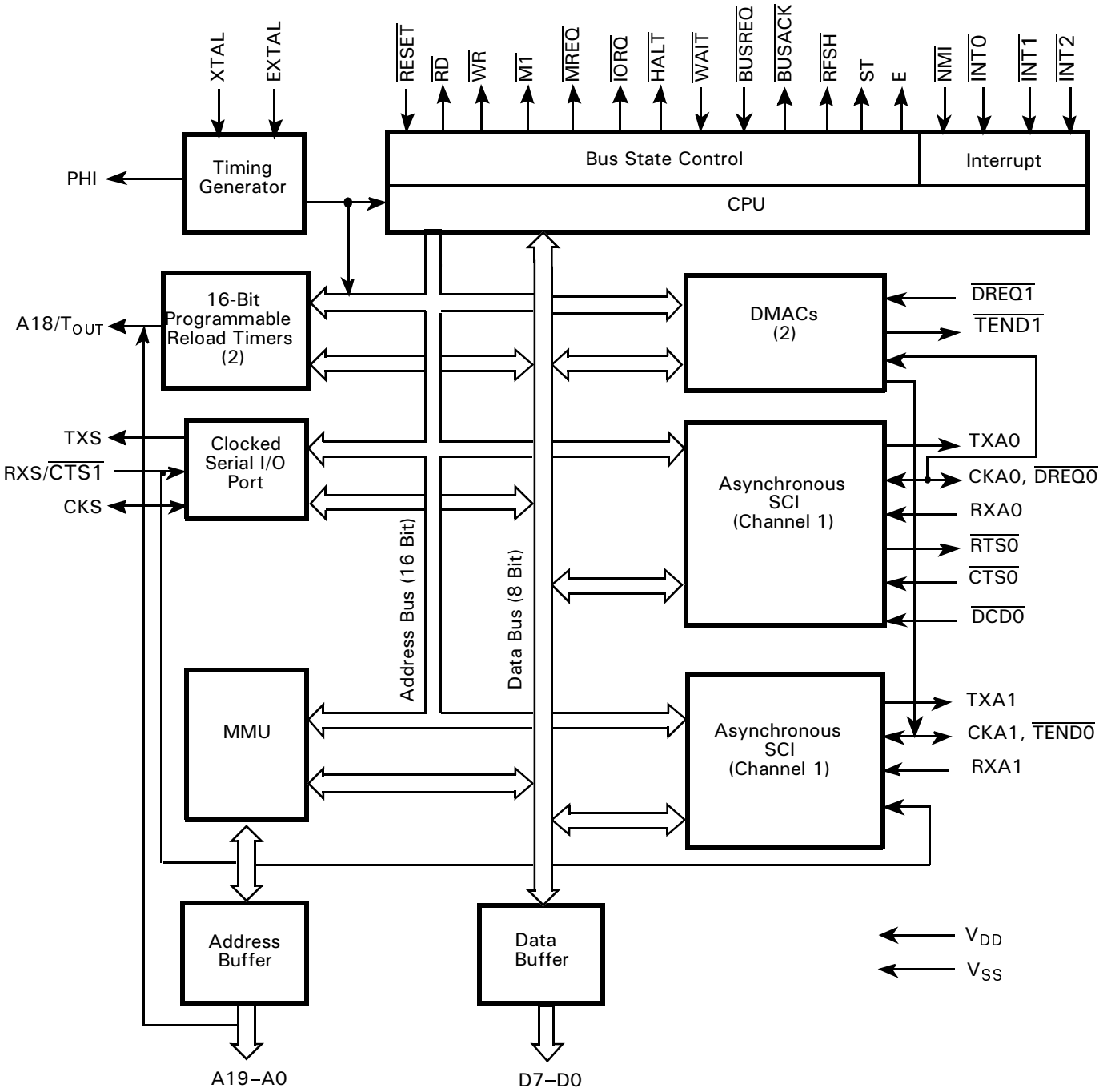

Figure 1. Z8S180/Z8L180 Functional Block Diagram

PIN IDENTIFICATION (Continued)

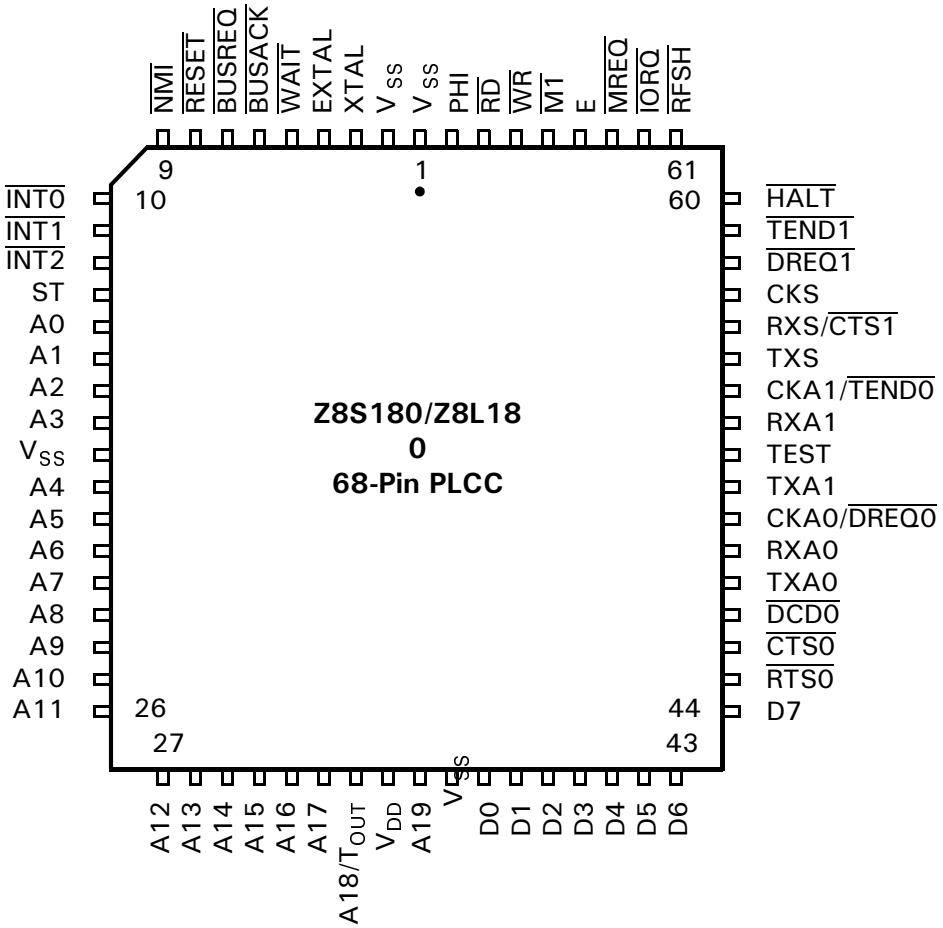

Figure 3. Z8S180/Z8L180 68-Pin PLCC Pin Configuration

PIN IDENTIFICATION (Continued)

Table 1. Z8S180/Z8L180 Pin Identification (Continued)

Pin Number and Package Type			Default	Secondary	
QFP	PLCC	DIP	Function	Function	Control
13	19	17	A4		
14			NC		
15	20	18	A5		
16	21	19	A6		
17	22	20	A7		
18	23	21	A8		
19	24	22	A9		
20	25	23	A10		
21	26	24	A11		
22			NC		
23			NC		
24	27	25	A12		
25	28	26	A13		
26	29	27	A14		
27	30	28	A15		
28	31	29	A16		
29	32	30	A17		
30			NC		
31	33	31	A18	T_{OUT}	Bit 2 or Bit 3 of TCR
32	34	32	V_{DD}		
33	35		A19		
34	36	33	V_{SS}		
35	37	34	D0		
36	38	35	D1		
37	39	36	D2		
38	40	37	D3		
39	41	38	D4		
40	42	39	D5		
41	43	40	D6		
42			NC		
43			NC		
44	44	41	D7		
45	45	42	$\overline{RTS0}$		
46	46	43	$\overline{CTS0}$		
47	47	44	$\overline{DCD0}$		
48	48	45	TXA0		
49	49	46	RXA0		
50	50	47	CKA0	$\overline{DREQ0}$	Bit 3 or Bit 5 of DMODE
51			NC		
52	51	48	TXA1		

Table 1. Z8S180/Z8L180 Pin Identification (Continued)

Pin Number and Package Type			Default	Secondary	
QFP	PLCC	DIP	Function	Function	Control
53	52		TEST		
54	53	49	RXA1		
55	54	50	CKA1	$\overline{\text{TEND0}}$	Bit 4 of CNTLA1
56	55	51	TXS		
57	56	52	RXS	$\overline{\text{CTS1}}$	Bit 2 of STAT1
58	57	53	CKS		
59	58	54	$\overline{\text{DREQ1}}$		
60	59	55	$\overline{\text{TEND1}}$		
61	60	56	$\overline{\text{HALT}}$		
62			NC		
63			NC		
64	61	57	$\overline{\text{RFSH}}$		
65	62	58	$\overline{\text{IORQ}}$		
66	63	59	$\overline{\text{MREQ}}$		
67	64	60	E		
68	65	61	$\overline{\text{M1}}$		
69	66	62	$\overline{\text{WR}}$		
70	67	63	$\overline{\text{RD}}$		
71	68	64	PHI		
72	1	1	V_{SS}		
73	2		V_{SS}		
74	3	2	XTAL		
75			NC		
76	4	3	EXTAL		
77	5	4	$\overline{\text{WAIT}}$		
78	6	5	$\overline{\text{BUSACK}}$		
79	7	6	$\overline{\text{BUSREQ}}$		
80	8	7	$\overline{\text{RESET}}$		

PIN IDENTIFICATION (Continued)

Table 2. Pin Status During RESET, BUSACK, and SLEEP Modes (Continued)

Pin Number and Package Type					Pin Status		
QFP	PLCC	DIP	Default Function	Secondary Function	RESET	BUSACK	SLEEP
76	4	3	EXTAL		IN	IN	IN
77	5	4	$\overline{\text{WAIT}}$		IN	IN	IN
78	6	5	$\overline{\text{BUSACK}}$		High	OUT	OUT
79	7	6	$\overline{\text{BUSREQ}}$		IN	IN	IN
80	8	7	$\overline{\text{RESET}}$		IN	IN	IN

PIN DESCRIPTIONS

A0–A19. Address Bus (Output, 3-state). A0–A19 form a 20-bit address bus. The Address Bus provides the address for memory data bus exchanges (up to 1 MB) and I/O data bus exchanges (up to 64 KB). The address bus enters a high–impedance state during reset and external bus acknowledge cycles. Address line A18 is multiplexed with the output of PRT channel 1 (T_{OUT}, selected as address output on reset), and address line A19 is not available in DIP versions of the Z8S180.

$\overline{\text{BUSACK}}$. Bus Acknowledge (Output, active Low). $\overline{\text{BUSACK}}$ indicates that the requesting device, the MPU address and data bus, and some control signals enter their high-impedance state.

BUSREQ. Bus Request (Input, active Low). This input is used by external devices (such as DMA controllers) to request access to the system bus. This request demands a higher priority than $\overline{\text{NMI}}$ and is always recognized at the end of the current machine cycle. This signal stops the CPU from executing further instructions, places addresses, data buses, and other control signals into the high-impedance state.

CKA0, CKA1. Asynchronous Clock 0 and 1 (bidirectional). When in output mode, these pins are the transmit and receive clock outputs from the ASCI baud rate generators. When in input mode, these pins serve as the external clock inputs for the ASCI baud rate generators. CKA0 is multiplexed with $\overline{\text{DREQ0}}$, and CKA1 is multiplexed with $\overline{\text{TEND0}}$.

CKS. Serial Clock (bidirectional). This line is the clock for the CSI/O channel.

$\overline{\text{CTS0}}$–$\overline{\text{CTS1}}$. Clear to send 0 and 1 (Inputs, active Low). These lines are modem control signals for the ASCI channels. $\overline{\text{CTS1}}$ is multiplexed with RXS.

D0–D7. Data Bus = (bidirectional, 3-state). D0–D7 constitute an 8-bit bidirectional data bus, used for the transfer of information to and from I/O and memory devices. The data bus enters the high-impedance state during reset and external bus acknowledge cycles.

$\overline{\text{DCD0}}$. Data Carrier Detect 0 (Input, active Low); a programmable modem control signal for ASCI channel 0.

$\overline{\text{DREQ0}}$, $\overline{\text{DREQ1}}$. DMA Request 0 and 1 (Input, active Low). $\overline{\text{DREQ}}$ is used to request a DMA transfer from one of the on-chip DMA channels. The DMA channels monitor these inputs to determine when an external device is ready for a READ or WRITE operation. These inputs can be programmed to be either level or edge sensed. $\overline{\text{DREQ0}}$ is multiplexed with CKA0.

E. Enable Clock (Output). This pin functions as a synchronous, machine-cycle clock output during bus transactions.

EXTAL. External Clock Crystal (Input). Crystal oscillator connections. An external clock can be input to the Z8S180/Z8L180 on this pin when a crystal is not used. This input is Schmitt triggered.

$\overline{\text{HALT}}$. HALT/SLEEP (Output, active Low). This output is asserted after the CPU executes either the HALT or SLEEP instruction and is waiting for either a nonmaskable or a maskable interrupt before operation can resume. It is also used with the $\overline{\text{M1}}$ and ST signals to decode the status of the CPU machine cycle.

$\overline{\text{INT0}}$. Maskable Interrupt Request 0 (Input, active Low). This signal is generated by external I/O devices. The CPU honors these requests at the end of the current instruction cycle as long as the $\overline{\text{NMI}}$ and $\overline{\text{BUSREQ}}$ signals are inactive. The CPU acknowledges this interrupt request with an interrupt acknowledge cycle. During this cycle, both the $\overline{\text{M1}}$ and $\overline{\text{IORQ}}$ signals become active.

$\overline{\text{INT1}}$, $\overline{\text{INT2}}$. Maskable Interrupt Request 1 and 2 (Inputs, active Low). This signal is generated by external I/O devices. The CPU honors these requests at the end of the current instruction cycle as long as the $\overline{\text{NMI}}$, $\overline{\text{BUSREQ}}$, and $\overline{\text{INT0}}$ signals are inactive. The CPU acknowledges these requests with an interrupt acknowledge cycle. Unlike the acknowledgment for $\overline{\text{INT0}}$, neither the $\overline{\text{M1}}$ or $\overline{\text{IORQ}}$ signals become active during this cycle.

$\overline{\text{IORQ}}$. I/O Request (Output, active Low, 3-state). $\overline{\text{IORQ}}$ indicates that the address bus contains a valid I/O address for an I/O READ or I/O WRITE operation. $\overline{\text{IORQ}}$ is also generated, along with $\overline{\text{M1}}$, during the acknowledgment of the $\overline{\text{INT0}}$ input signal to indicate that an interrupt response vector can be place onto the data bus. This signal is analogous to the $\overline{\text{IOE}}$ signal of the Z64180.

$\overline{\text{M1}}$. Machine Cycle 1 (Output, active Low). Together with $\overline{\text{MREQ}}$, $\overline{\text{M1}}$ indicates that the current cycle is the opcode-fetch cycle of instruction execution. Together with $\overline{\text{IORQ}}$, $\overline{\text{M1}}$ indicates that the current cycle is for interrupt acknowledgment. It is also used with the $\overline{\text{HALT}}$ and ST signal to decode the status of the CPU machine cycle. This signal is analogous to the $\overline{\text{LIR}}$ signal of the Z64180.

$\overline{\text{MREQ}}$. Memory Request (Output, active Low, 3-state). $\overline{\text{MREQ}}$ indicates that the address bus holds a valid address for a memory READ or memory WRITE operation. This signal is analogous to the $\overline{\text{ME}}$ signal of Z64180.

$\overline{\text{NMI}}$. Nonmaskable Interrupt (Input, negative edge triggered). $\overline{\text{NMI}}$ demands a higher priority than $\overline{\text{INT}}$ and is al-

PIN DESCRIPTIONS (Continued)

ways recognized at the end of an instruction, regardless of the state of the interrupt-enable flip-flops. This signal forces CPU execution to continue at location 0066H.

PHI. System Clock (Output). The output is used as a reference clock for the MPU and the external system. The frequency of this output may be one-half, equal to, or twice the crystal or input clock frequency.

$\overline{RD}$. Read (Output, active Low, 3-state). $\overline{RD}$ indicates that the CPU wants to read data from either memory or an I/O device. The addressed I/O or memory device should use this signal to gate data onto the CPU data bus.

$\overline{RFSH}$. Refresh (Output, active Low). Together with $\overline{MREQ}$, $\overline{RFSH}$ indicates that the current CPU machine cycle and the contents of the address bus should be used for refresh of dynamic memories. The low-order 8 bits of the address bus (A7–A0) contain the refresh address. *This signal is analogous to the $\overline{REF}$ signal of the Z64180.*

$\overline{RTS0}$. Request to Send 0 (Output, active Low); a programmable MODEM control signal for ASCI channel 0.

RXA0, RXA1. Receive Data 0 and 1 (Input). These signals are the receive data for the ASCI channels.

RXS. Clocked Serial Receive Data (Input). This line is the receive data for the CSI/O channel. RXS is multiplexed with the $\overline{CTS1}$ signal for ASCI channel 1.

ST. Status (Output). This signal is used with the $\overline{M1}$ and $\overline{HALT}$ output to decode the status of the CPU machine cycle. See Table 3.

Table 3. Status Summary

ST	$\overline{HALT}$	$\overline{M1}$	Operation
0	1	0	CPU Operation (1st Opcode Fetch)
1	1	0	CPU Operation (2nd Opcode and 3rd Opcode Fetch)
1	1	1	CPU Operation (MC Except Opcode Fetch)
0	X	1	DMA Operation
0	0	0	HALT Mode
1	0	1	SLEEP Mode (Including SYSTEM STOP Mode)

Notes:
X = Do not care.
MC = Machine Cycle.

$\overline{TEND0}$, $\overline{TEND1}$. Transfer End 0 and 1 (Outputs, active Low). This output is asserted active during the most recent WRITE cycle of a DMA operation. It is used to indicate the end of the block transfer. $\overline{TEND0}$ is multiplexed with CKA1.

TEST. Test (Output, not in DIP version). This pin is for test and should be left open.

T_{OUT}. Timer Out (Output). T_{OUT} is the output from PRT channel 1. This line is multiplexed with A18 of the address bus.

TXA0, TXA1. Transmit Data 0 and 1 (Outputs). These signals are the transmitted data from the ASCI channels. Transmitted data changes are with respect to the falling edge of the transmit clock.

TXS. Clocked Serial Transmit Data (Output). This line is the transmitted data from the CSI/O channel.

$\overline{WAIT}$. Wait (Input, active Low). $\overline{WAIT}$ indicates to the MPU that the addressed memory or I/O devices are not ready for data transfer. This input is sampled on the falling edge of T2 (and subsequent WAIT states). If the input is sampled Low, then the additional WAIT states are inserted until the $\overline{WAIT}$ input is sampled High, at which time execution continues.

$\overline{WR}$. WRITE (Output, active Low, 3-state). $\overline{WR}$ indicates that the CPU data bus holds valid data to be stored at the addressed I/O or memory location.

XTAL. Crystal Oscillator Connection (Input). This pin should be left open if an external clock is used instead of a crystal. The oscillator input is not a TTL level (see DC Characteristics).

Several pins are used for different conditions, depending on the circumstance.

ARCHITECTURE (Continued)

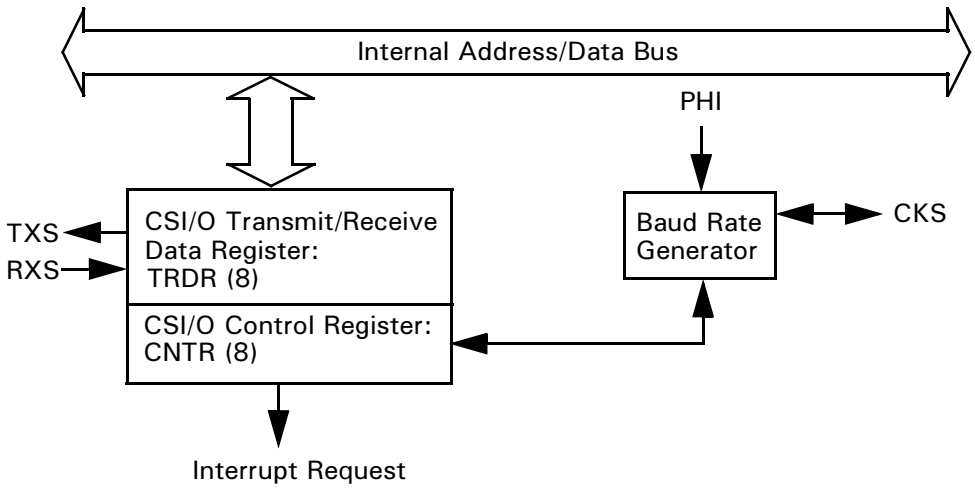

Figure 7. CSI/O Block Diagram

OPERATION MODES (Continued)

Table 5. RETI Control Signal States

Machine Cycle	States	Address	Data	$\overline{RD}$	$\overline{WR}$	$\overline{MREQ}$	$\overline{IORQ}$	$\overline{M1}$ M1E = 1	$\overline{M1}$ M1E = 0	$\overline{HALT}$	ST
1	T1–T3	1st Opcode	EDH	0	1	0	1	0	1	1	0
2	T1–T3	2nd Opcode	4DH	0	1	0	1	0	1	1	0
	Ti	NA	3-state	1	1	1	1	1	1	1	1
	Ti	NA	3-state	1	1	1	1	1	1	1	1
	Ti	NA	3-state	1	1	1	1	1	1	1	1
3	T1–T3	1st Opcode	EDH	0	1	0	1	0	0	1	1
	Ti	NA	3-state	1	1	1	1	1	1	1	1
4	T1–T3	2nd Opcode	4DH	0	1	0	1	0	1	1	1
5	T1–T3	SP	Data	0	1	0	1	1	1	1	1
6	T1–T3	SP + 1	Data	0	1	0	1	1	1	1	1

$\overline{M1TE}$ ($\overline{M1}$ Temporary Enable). This bit controls the temporary assertion of the $\overline{M1}$ signal. It is always read back as a 1 and is set to 1 during RESET.

When M1E is set to 0 to accommodate certain external Z80 peripheral(s), those same device(s) may require a pulse on $\overline{M1}$ after programming certain of their registers to complete the function being programmed.

For example, when a control word is written to the Z80 PIO to enable interrupts, no enable actually takes place until the PIO sees an active $\overline{M1}$ signal. When $\overline{M1TE}$ = 1, there is no change in the operation of the $\overline{M1}$ signal, and M1E controls its function. When $\overline{M1TE}$ = 0, the $\overline{M1}$ output is asserted during the next opcode fetch cycle regardless of the state programmed into the M1E bit. This condition is only momentary (one time) and it is not necessary to preprogram a 1 to disable the function (see Figure 10).

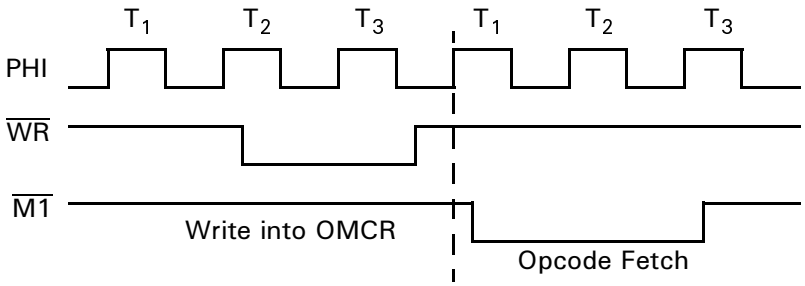

Figure 10. M1 Temporary Enable Timing

IOC (I/O Compatibility). This bit controls the timing of the $\overline{IORQ}$ and $\overline{RD}$ signals. The bit is set to 1 by RESET.

When $\overline{IOC}$ = 1, the $\overline{IORQ}$ and $\overline{RD}$ signals function the same as the Z64180 (Figure 11).

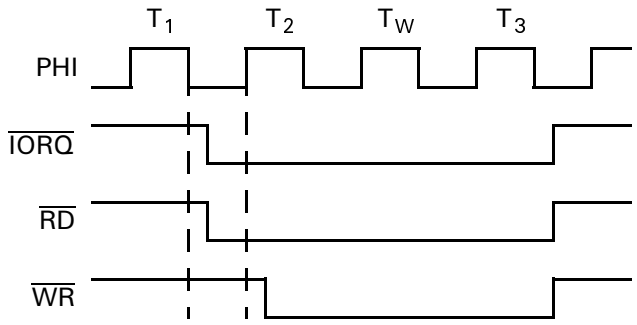

Figure 11. I/O Read and Write Cycles with $\overline{IOC}$ = 1

When $\overline{IOC}$ = 0, the timing of the $\overline{IORQ}$ and $\overline{RD}$ signals match the timing of the Z80. The $\overline{IORQ}$ and $\overline{RD}$ signals go active as a result of the rising edge of T2. (Figure 12.)

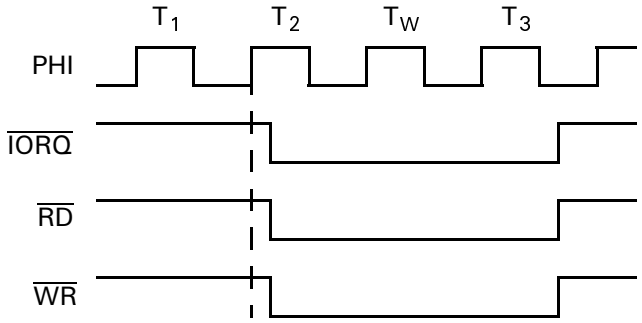

Figure 12. I/O Read and Write Cycles with $\overline{IOC}$ = 0

HALT and Low-Power Operating Modes. The Z8S180/Z8L180 can operate in seven modes with respect to activity and power consumption:

- Normal Operation
- HALT Mode
- IOSTOP Mode
- SLEEP Mode
- SYSTEM STOP Mode
- IDLE Mode
- STANDBY Mode (with or without QUICK RECOVERY)

Normal Operation. In this state, the Z8S180/Z8L180 processor is fetching and running a program. All enabled functions and portions of the device are active, and the $\overline{HALT}$ pin is High.

HALT Mode. This mode is entered by the HALT instruction. Thereafter, the Z8S180/Z8L180 processor continually fetches the following opcode but does not execute it and drives the $\overline{HALT}$, ST and $\overline{M1}$ pins all Low. The oscillator and PHI pin remain Active. Interrupts and bus granting to external Masters, and DRAM refresh can occur, and all on-chip I/O devices continue to operate including the DMA channels.

DC CHARACTERISTICS—Z8S180

Table 6. Z8S180 DC Characteristics
V_{DD} = 5V ±10%; V_{SS} = 0V

Symbol	Item	Condition	Min	Typ	Max	Unit
V_{IH1}	Input H Voltage $\overline{RESET}$, EXTAL, $\overline{NMI}$		V_{DD} –0.6	—	V_{DD} +0.3	V
V_{IH2}	Input H Voltage Except $\overline{RESET}$, EXTAL, $\overline{NMI}$		2.0	—	V_{DD} +0.3	V
V_{IH3}	Input H Voltage CKS, CKA0, CKA1		2.4	—	V_{DD} +0.3	V
V_{IL1}	Input L Voltage RESET, EXTAL, NMI		–0.3	—	0.6	V
V_{IL2}	Input L Voltage Except RESET, EXTAL, NMI		–0.3	—	0.8	V
V_{OH}	Outputs H Voltage All outputs	I_{OH} = –200 µA	2.4	—	—	V
		I_{OH} = –20 µA	V_{DD} –1.2	—	—	
V_{OL}	Outputs L Voltage All outputs	I_{OL} = 2.2 mA	—	—	0.45	V
I_{IL}	Input Leakage Current All Inputs Except XTAL, EXTAL	V_{IN} = 0.5 ~ V_{DD} –0.5	—	—	1.0	µA
I_{TL}	Three State Leakage Current	V_{IN} = 0.5 ~ V_{DD} –0.5	—	—	1.0	µA
I_{DD}[1]	Power Dissipation (Normal Operation)	F = 10 MHz	—	25	60	mA
		20		30	50	
		33		60	100	
	Power Dissipation (SYSTEM STOP mode)	F = 10 MHz	—	2	5	
		20		3	6	
		33		5	9	
C_P	Pin Capacitance	V_{IN} = 0_V, f = 1 MHz T_A = 25°C	—	—	12	pF

Note:
1. V_{IHmin} = V_{DD}–1.0V, V_{ILmax} = 0.8V (All output terminals are at NO LOAD.) V_{DD} = 5.0V.

AC CHARACTERISTICS—Z8S180

Table 8. Z8S180 AC Characteristics
V_{DD} = 5V ±10% or V_{DD} = 3.3V ±10%; 33-MHz Characteristics Apply Only to 5V Operation

			Z8S180—20 MHz		Z8S180—33 MHz		
Number	**Symbol**	**Item**	**Min**	**Max**	**Min**	**Max**	**Unit**
1	t_{CYC}	Clock Cycle Time	50	DC	30	DC	ns
2	t_{CHW}	Clock "H" Pulse Width	15	—	10	—	ns
3	t_{CLW}	Clock "L" Pulse Width	15	—	10	—	ns
4	t_{CF}	Clock Fall Time	—	10	—	5	ns
5	t_{CR}	Clock Rise Time	—	10	—	5	ns
6	t_{AD}	PHI Rise to Address Valid Delay	—	30	—	15	ns
7	t_{AS}	Address Valid to $\overline{MREQ}$ Fall or $\overline{IORQ}$ Fall)	5	—	5	—	ns
8	t_{MED1}	PHI Fall to $\overline{MREQ}$ Fall Delay	—	25	—	15	ns
9	t_{RDD1}	PHI Fall to $\overline{RD}$ Fall Delay $\overline{IOC}$ = 1	—	25	—	15	ns
		PHI Rise to $\overline{RD}$ Rise Delay $\overline{IOC}$ = 0	—	25	—	15	
10	t_{M1D1}	PHI Rise to $\overline{M1}$ Fall Delay	—	35	—	15	ns
11	t_{AH}	Address Hold Time from $\overline{MREQ}$, $\overline{IOREQ}$, $\overline{RD}$, $\overline{WR}$ High	5	—	5	—	ns
12	t_{MED2}	PHI Fall to $\overline{MREQ}$ Rise Delay	—	25	—	15	ns
13	t_{RDD2}	PHI Fall to $\overline{RD}$ Rise Delay	—	25	—	15	ns
14	t_{M1D2}	PHI Rise to $\overline{M1}$ Rise Delay	—	40	—	15	ns
15	t_{DRS}	Data Read Set-up Time	10	—	5	—	ns
16	t_{DRH}	Data Read Hold Time	0	—	0	—	ns
17	t_{STD1}	PHI Fall to ST Fall Delay	—	30	—	15	ns
18	t_{STD2}	PHI Fall to ST Rise Delay	—	30	—	15	ns
19	t_{WS}	$\overline{WAIT}$ Set-up Time to PHI Fall	15	—	10	—	ns
20	t_{WH}	$\overline{WAIT}$ Hold Time from PHI Fall	10	—	5	—	ns
21	t_{WDZ}	PHI Rise to Data Float Delay	—	35	—	20	ns
22	t_{WRD1}	PHI Rise to $\overline{WR}$ Fall Delay	—	25	—	15	ns
23	t_{WDD}	PHI Fall to Write Data Delay Time	—	25	—	15	ns
24	t_{WDS}	Write Data Set-up Time to $\overline{WR}$ Fall	10	—	10	—	ns
25	t_{WRD2}	PHI Fall to $\overline{WR}$ Rise Delay	—	25	—	15	ns
26	t_{WRP}	$\overline{WR}$ Pulse Width (Memory Write Cycle)	80	—	45	—	ns
26a		$\overline{WR}$ Pulse Width (I/O Write Cycle)	150	—	70	—	ns
27	t_{WDH}	Write Data Hold Time from $\overline{WR}$ Rise	10	—	5	—	ns
28	t_{IOD1}	PHI Fall to $\overline{IORQ}$ Fall Delay $\overline{IOC}$ = 1	—	25	—	15	ns
		PHI Rise to $\overline{IORQ}$ Fall Delay $\overline{IOC}$ = 0	—	25	—	15	
29	t_{IOD2}	PHI Fall to $\overline{IORQ}$ Rise Delay	—	25	—	15	ns
30	t_{IOD3}	$\overline{M1}$ Fall to $\overline{IORQ}$ Fall Delay	125	—	80	—	ns
31	t_{INTS}	$\overline{INT}$ Set-up Time to PHI Fall	20	—	15	—	ns

Table 8. Z8S180 AC Characteristics (Continued)
V_{DD} = 5V ±10% or V_{DD} = 3.3V ±10%; 33-MHz Characteristics Apply Only to 5V Operation

			Z8S180—20 MHz		Z8S180—33 MHz		
Number	**Symbol**	**Item**	**Min**	**Max**	**Min**	**Max**	**Unit**
63	t_{REH}	$\overline{RESET}$ Hold Time from PHI Fall	25	—	15	—	ns
64	t_{OSC}	Oscillator Stabilization Time	—	20	—	20	ns
65	t_{EXR}	External Clock Rise Time (EXTAL)	—	5	—	5	ns
66	t_{EXF}	External Clock Fall Time (EXTAL)	—	5	—	5	ns
67	t_{RR}	$\overline{RESET}$ Rise Time	—	50	—	50	ms
68	t_{RF}	$\overline{RESET}$ Fall Time	—	50	—	50	ms
69	t_{IR}	Input Rise Time (except EXTAL, $\overline{RESET}$)	—	50	—	50	ns
70	t_{IF}	Input Fall Time (except EXTAL, $\overline{RESET}$)	—	50	—	50	ns

TIMING DIAGRAMS (Continued)

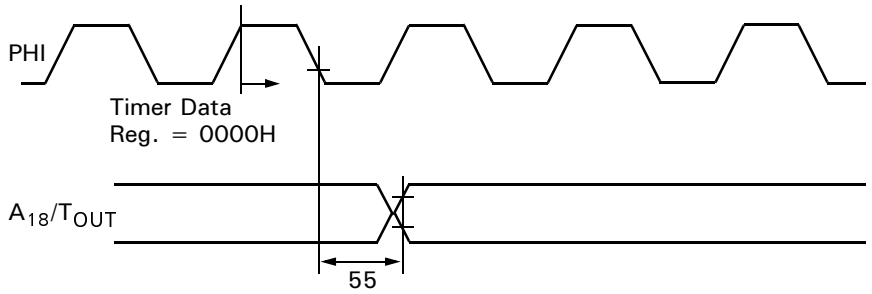

Figure 27. Timer Output Timing

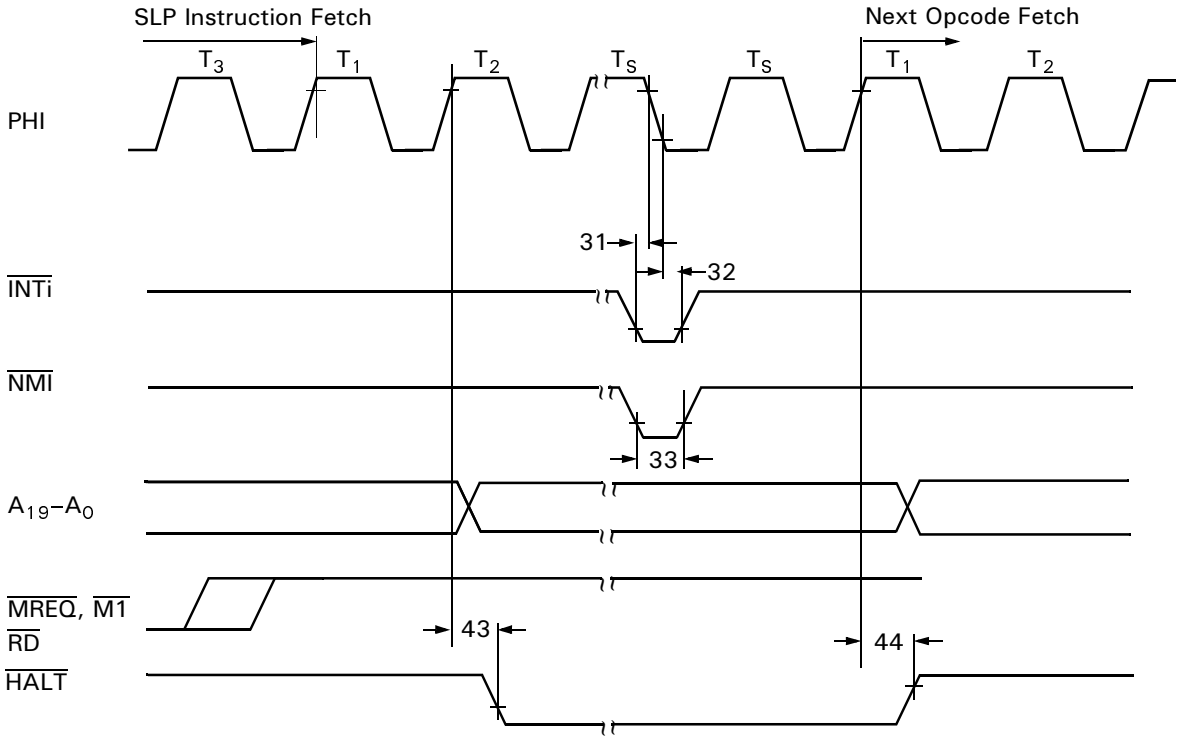

Figure 28. SLP Execution Cycle

CPU CONTROL REGISTER

CPU Control Register (CCR). This register controls the basic clock rate, certain aspects of Power-Down modes, and output drive/low-noise options (Figure 31).

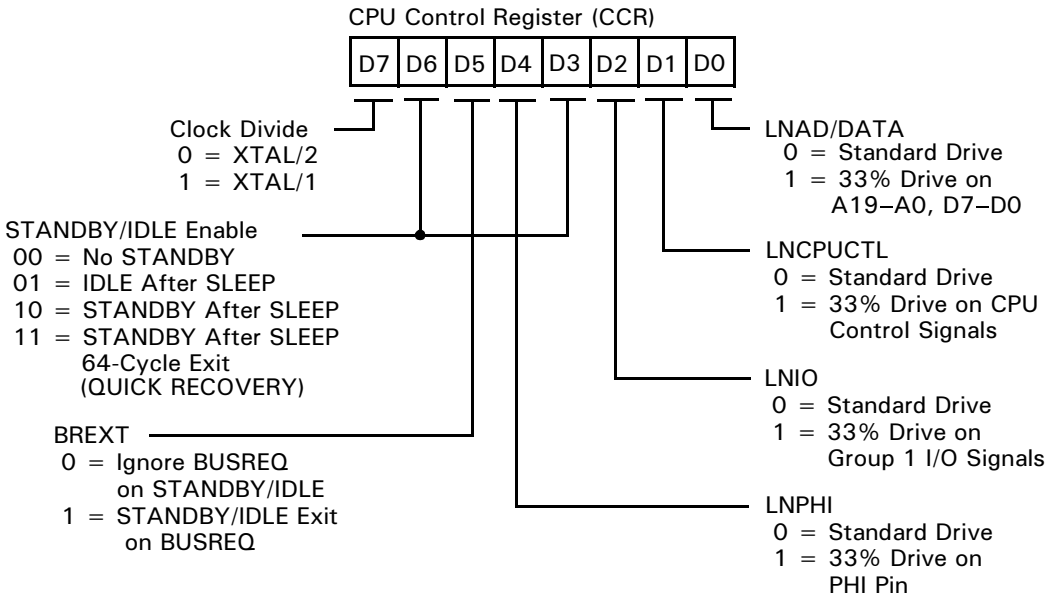

Figure 31. CPU Control Register (CCR) Address 1FH

Bit 7. Clock Divide Select. If this bit is 0, as it is after a RESET, the Z8S180/Z8L180 divides the frequency on the XTAL pin(s) by two to obtain its Master clock PHI. If this bit is programmed as 1, the part uses the XTAL frequency as PHI without division.

If an external oscillator is used in divide-by-one mode, the minimum pulse width requirement provided in the AC Characteristics must be satisfied.

Bits 6 and 3. STANDBY/IDLE Control. When these bits are both 0, a SLP instruction makes the Z8S180/Z8L180 enter SLEEP or SYSTEM STOP mode, depending on the IOSTOP bit (ICR5).

When D6 is 0 and D3 is 1, setting the IOSTOP bit (ICR5) and executing a SLP instruction puts the Z8S180/Z8L180 into IDLE mode in which the on-chip oscillator runs, but its output is blocked from the rest of the part, including PHI out.

When D6 is 1 and D3 is 0, setting IOSTOP (ICR5) and executing a SLP instruction puts the part into STANDBY mode, in which the on-chip oscillator is stopped and the part allows 2^{17} (128K) clock cycles for the oscillator to stabilize when it restarts.

When D6 and D3 are both 1, setting IOSTOP (ICR5) and executing a SLP instruction puts the part into QUICK RECOVERY STANDBY mode, in which the on-chip oscillator is stopped, and the part allows only 64 clock cycles for the oscillator to stabilize when it restarts.

The latter section, HALT and LOW POWER modes, describes the subject more fully.

Bit 5 BREXT. This bit controls the ability of the Z8S180/Z8L180 to honor a bus request during STANDBY mode. If this bit is set to 1 and the part is in STANDBY mode, a BUSREQ is honored after the clock stabilization timer is timed out.

Bit 4 LNPHI. This bit controls the drive capability on the PHI Clock output. If this bit is set to 1, the PHI Clock output is reduced to 33 percent of its drive capability.

TIMER CONTROL REGISTER

The Timer Control Register (TCR) monitors both channels (PRT0, PRT1) TMDR status. It also controls the enabling and disabling of down-counting and interrupts, and controls the output pin A18/T_{OUT} for PRT1.

Bit	7	6	5	4	3	2	1	0
	TIF1	TIF0	TIE1	TIE0	TOC1	TOC0	TDE1	TDE0
	R	R	R/W	R/W	R/W	R/W	R/W	R/W

Figure 46. Timer Control Register (TCR: I/O Address = 10H)

TIF1: Timer Interrupt Flag 1 (Bit 7) . When TMDR1 decrements to 0, TIF1 is set to 1. This condition generates an interrupt request if enabled by TIE1 = 1. TIF1 is reset to 0 when TCR is read and the higher or lower byte of TMDR1 is read. During RESET, TIF1 is cleared to 0.

TIF0: Timer Interrupt Flag 0 (Bit 6). When TMDR0 decrements to 0, TIF0 is set to 1. This condition generates an interrupt request if enabled by TIE0 = 1. TIF0 is reset to 0 when TCR is read and the higher or lower byte of TMDR0 is read. During RESET, TIF0 is cleared to 0.

TIE1: Timer Interrupt Enable 1 (Bit 5). When TIE0 is set to 1, TIF1 = 1 generates a CPU interrupt request. When TIE0 is reset to 0, the interrupt request is inhibited. During RESET, TIE0 is cleared to 0.

TOC1, 0: Timer Output Control (Bits 3, 2). TOC1 and TOC0 control the output of PRT1 using the multiplexed A18/T_{OUT} pin as indicated in Table 12. During RESET, TOC1 and TOC0 are cleared to 0. If bit 3 of the IAR1B register is 1, the T_{OUT} function is selected. By programming TOC1 and TOC0, the A18/T_{OUT} pin can be forced High, Low, or toggled when TMDR1 decrements to 0.

Table 12. Timer Output Control

TOC1	TOC0	Output	
0	0	Inhibited	The A18/T_{OUT} pin is not affected by the PRT
0	1	Toggled	If bit 3 of IAR1B is 1, the A18/T_{OUT} pin is toggled or set Low or High as indicated
1	0	0	
1	1	1	

TDE1, 0: Timer Down Count Enable (Bits 1, 0). TDE1 and TDE0 enable and disable down-counting for TMDR1 and TMDR0, respectively. When TDEn (n = 0,1) is set to 1, down-counting is stopped and TMDRn is freely read or written. TDE1 and TDE0 are cleared to 0 during RESET and TMDRn does not decrement until TDEn is set to 1.

DMA BYTE COUNT REGISTER CHANNEL 0

The DMA Byte Count Register Channel 0 specifies the number of bytes to be transferred. This register contains 16 bits and may specify up to 64-KB transfers. When one byte is transferred, the register is decremented by one. If n bytes should be transferred, n must be stored before the DMA operation.

Note: All DMA Count Register channels are undefined during RESET.

DMA Byte Count Register Channel 0 Low

Mnemonic BCR0L
Address 26H

Figure 61. DMA Byte Count Register 0 Low

DMA Byte Count Register Channel 0 High

Mnemonic BCR0H
Address 27H

Figure 62. DMA Byte Count Register 0 High

DMA Byte Count Register Channel 1 Low

Mnemonic BCR1L
Address 2EH

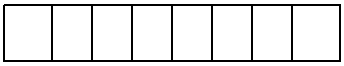

Figure 63. DMA Byte Count Register 1 Low

DMA Byte Count Register Channel 1 High

Mnemonic BCR1H
Address 2FH

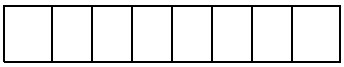

Figure 64. DMA Byte Count Register 1 High

DMA MEMORY ADDRESS REGISTER CHANNEL 1

The DMA Memory Address Register Channel 1 specifies the physical memory address for channel 1 transfers. The address may be a destination or a source memory location. The register contains 20 bits and may specify up to 1024 KB memory addresses.

DMA Memory Address Register, Channel 1L

Mnemonic MAR1L
Address 28H

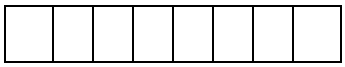

Figure 65. DMA Memory Address Register, Channel 1L

DMA Memory Address Register, Channel 1H

Mnemonic MAR1H
Address 29H

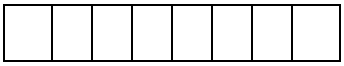

Figure 66. DMA Memory Address Register, Channel 1H

DMA Memory Address Register, Channel 1B

Mnemonic MAR1B
Address 2AH

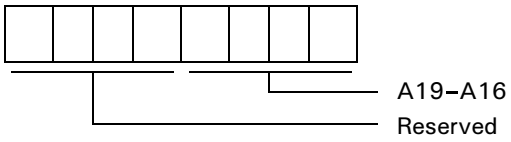

Figure 67. DMA Memory Address Register, Channel 1B

DMA/WAIT CONTROL REGISTER

The DMA/WAIT Control Register (DCNTL) controls the insertion of wait states into DMAC (and CPU) accesses of memory or I/O. Also, the register defines the Request signal for each channel as level or edge sense. DCNTL also sets the DMA transfer mode for channel 1, which is limited to memory to/from I/O transfers.

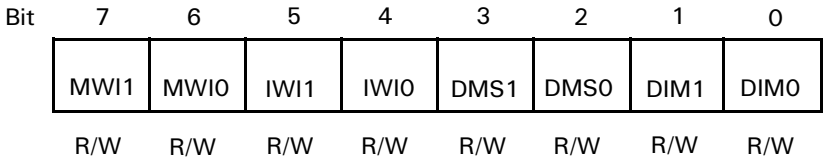

Figure 73. DMA/WAIT Control Register (DCNTL: I/O Address = 32H)

MWI1, MWI0: Memory Wait Insertion (Bits 7–6). This bit specifies the number of wait states introduced into CPU or DMAC memory access cycles. MWI1 and MWI0 are set to 1 during RESET.

MWI1	MWI0	Wait State
0	0	0
0	1	1
1	0	2
1	1	3

IWI1, IWI0: I/O Wait Insertion (Bits 5–4). This bit specifies the number of wait states introduced into CPU or DMAC I/O access cycles. IWI1 and IWI0 are set to 1 during RESET.

IWI1	IWI0	Wait State
0	0	1
0	1	2
1	0	3
1	1	4

Note: These wait states are added to the 3-clock I/O cycle that is used to access the on-chip I/O registers. It is equally valid to regard these as 0 to 3 wait states added to a 4-clock external I/O cycle.

DMS1, DMS0: DMA Request Sense (Bits 3–2). DMS1 and DMS0 specify the DMA request sense for channel 0 and channel 1 respectively. When reset to 0, the input is level sense. When set to 1, the input is edge sense. DMS1 and DMS0 are cleared to 0 during RESET.

DMSi	Sense
1	Edge Sense
0	Level Sense

Typically, for an input/source device, the associated DMS bit should be programmed as 0 for level sense. The device takes a relatively long time to update its Request signal after the DMA channel reads data (in the first of the two machine cycles involved in transferring a byte).

An output/destination device takes much less time to update its Request signal after the DMA channel starts a WRITE operation to it (the second machine cycle of the two cycles involved in transferring a byte). With zero-wait state I/O cycles, a device cannot update its request signal in the required time, so edge sensing must be used.

A one-wait-state I/O cycle also does not provide sufficient time for updating, so edge sensing is again required.

DIM1, DIM0: DMA Channel 1 I/O and Memory Mode (Bits 1–0). Specifies the source/destination and address modifier for channel 1 memory to/from I/O transfer modes. DIM1 and DIM0 are cleared to 0 during RESET.

Table 17. Channel 1 Transfer Mode

DIM1	DMI0	Transfer Mode	Address Increment/Decrement
0	0	Memory→I/O	MAR1 +1, IAR1 fixed
0	1	Memory→I/O	MAR1 –1, IAR1 fixed
1	0	I/O→Memory	IAR1 fixed, MAR1 +1
1	1	I/O→Memory	IAR1 fixed, MAR1 –1

I/O CONTROL REGISTER

The I/O Control Register (ICR) allows relocation of the internal I/O addresses. ICR also controls the enabling and disabling of IOSTOP mode (Figure 83).

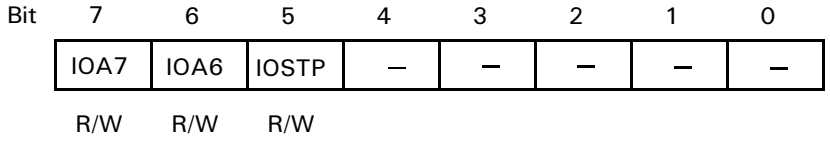

Figure 83. I/O Control Register (ICR: I/O Address = 3FH)

IOA7, 6: I/O Address Relocation (Bits 7,6). IOA7 and IOA6 relocate internal I/O as indicated in Figure 84.

Note: The high-order 8 bits of 16-bit internal I/O address are always 0. IOA7 and IOA6 are cleared to 0 during RESET.

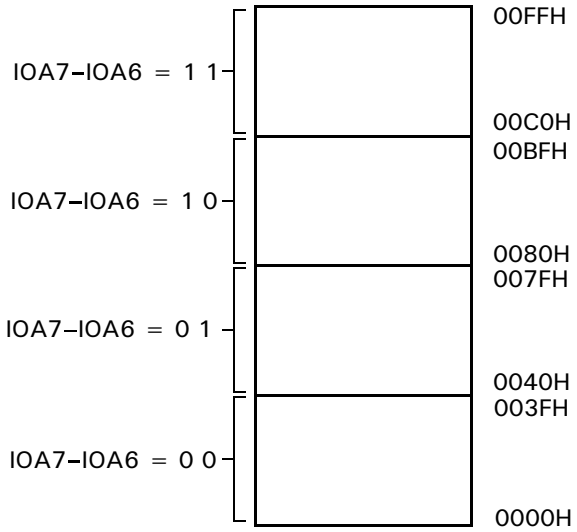

Figure 84. I/O Address Relocation

IOSTP: IOSTOP Mode (Bit 5). IOSTOP mode is enabled when IOSTP is set to 1. Normal I/O operation resumes when IOSTP is reprogrammed or RESET to 0.